

MATERIAL SET CHANGE

Carsem

MS011435A	Die 1	Die 2
Die Size X	3175	3327
Die Size Y	3098	5410
Adhesive Material	Ablestik 84-1 LMISR4 conductive	
Mold Compound	Sumitomo G600C	
Die Coat Material	N/A	Dow Corning 4939

Amkor Philippines

MS012533A	Die 1	Die 2
Die Size X	3175	3327
Die Size Y	3098	5410
Adhesive Material	Ablestik 84-3J non-conductive	Ablestik 8290 conductive
Mold Compound	Sumitomo G600	
Die Coat Material	N/A	Dow Corning 4939

AD677 Leadframe Change from Split pad to Single Pad in 300_MIL PDIP Package

Qualification Results Summary for AD677 in 16L PDIP at Amkor Philippines

QUALIFICATION RESULT			
TEST	SPECIFICATION	SAMPLE SIZE	RESULT
Temperature Cycle (TC)*	JEDEC <i>JESD22-A104</i>	3 x 77	PASS
Unbiased Highly Accelerated Stress Test (uHAST)*	JEDEC <i>JESD22-A118</i>	3 x 77	PASS
Solder Heat Resistance (SHR)*	JEDEC/IPC <i>J-STD-020</i>	3 x 11	PASS
High Temperature Storage (HTS)	JEDEC <i>JESD22-A103</i>	1 x 77	PASS
Electrostatic Discharge <i>Field Induced Charge Device Model</i>	JEDEC <i>JESD22-C101</i>	3/voltage	PASS ±500V

*Preconditioned per JEDEC/IPC J-STD-020